

THS4061 High-Speed Operational Amplifier Evaluation Module

User's Guide

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Preface

Related Documentation From Texas Instruments

- ***THS4061 HIGH-SPEED LOW-POWER OPERATIONAL AMPLIFIER*** (literature number SLOS234) This is the data sheet for the THS4061 operational amplifier integrated circuit that is used in the THS4061 evaluation module.

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General

This chapter details the Texas Instruments (TI™) THS4061 High-Speed Operational Amplifier Evaluation Module (EVM), SLOP226. It includes a list of EVM features, a brief description of the module illustrated with a pictorial and a schematic diagram, EVM specifications, details on connecting and using the EVM, and a discussion on high-speed amplifier design considerations.

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1.1 Feature Highlights

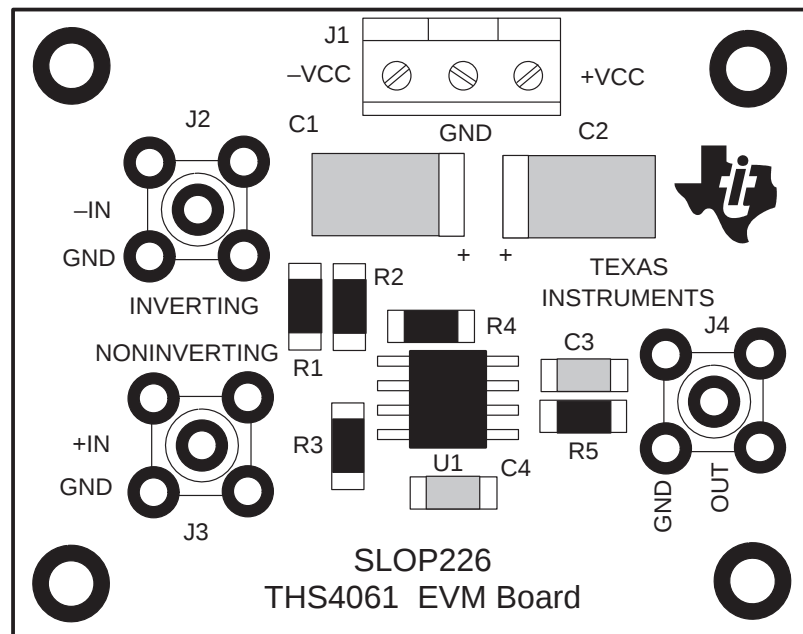
THS4061 High-Speed Operational Amplifier EVM features include:

- High Bandwidth — 75 MHz, -3 dB @ $\pm 15 V_{CC}$ & Gain = 2
- ± 5 -V to ± 15 -V Operation
- Inverting and Noninverting Single-Ended Inputs
- Module Gain Set to +2 (Noninverting) and -1 (Inverting) — Adjustable Through Component Change.
- Nominal 50- Ω Impedance Inputs and Outputs
- Standard SMA Miniature RF Connectors
- Good Example of High-Speed Amplifier Design and Layout

1.2 Description

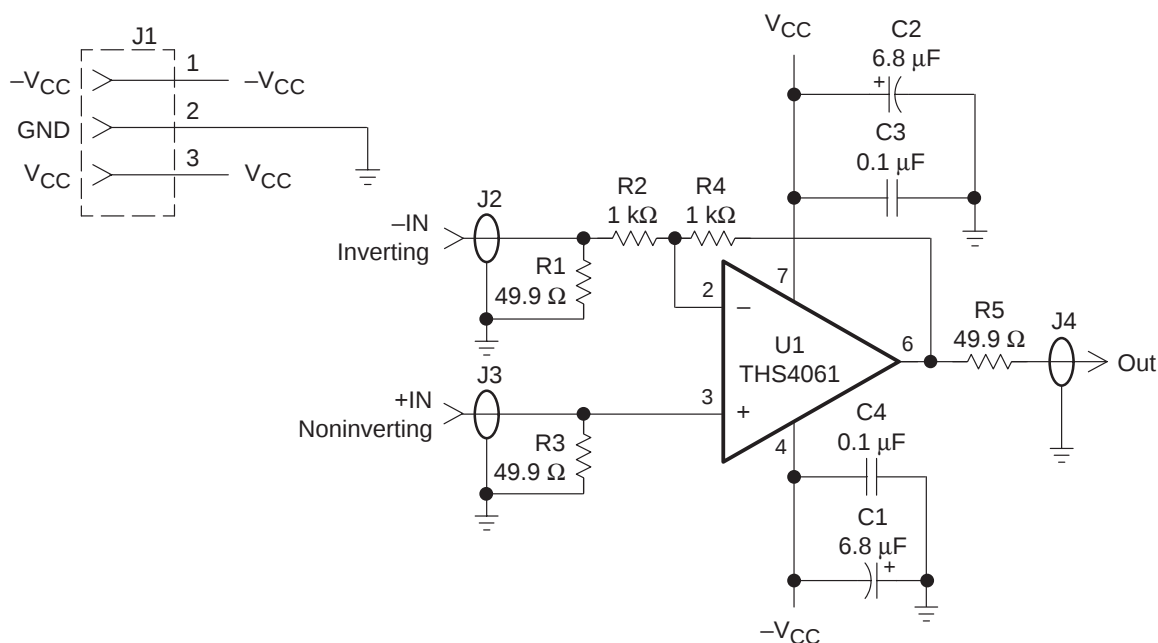
The TI THS4061 High-Speed Operational Amplifier Evaluation Module (EVM) is a complete high-speed amplifier circuit. It consists of the TI THS4061 High-Speed, Low-Power Operational Amplifier IC, along with a small number of passive parts, mounted on a small circuit board measuring approximately 1.7 inch by 1.4 inch (Figure 1–1). The EVM uses standard SMA miniature RF connectors for inputs and outputs and is completely assembled, fully tested, and ready to use — just connect it to power, a signal source, and a load (if desired).

Figure 1–1. THS4061 Evaluation Module



The THS4061 EVM is equipped with both noninverting and inverting inputs. The noninverting input is set for a gain of +2 and the inverting input is set for a gain of -1. Each input is terminated with a 50-Ω resistor to provide correct line impedance matching (Figure 1–2). The amplifier IC output is routed through a 50-Ω resistor both to provide correct line impedance matching and to help isolate capacitive loading on the output of the amplifier. Capacitive loading directly on the output of the IC decreases the amplifier's phase margin and can result in peaking or oscillations.

Figure 1–2. THS4061 EVM Schematic



The gain of the EVM inputs can easily be changed to support a particular application by simply changing the ratio of resistors R1, R4, and R5 as described in the following equations:

$$\text{Inverting Gain} = \frac{-R_F}{R_G} = \frac{-R_4}{R_2}$$

$$\text{Noninverting Gain} = 1 + \frac{R_F}{R_G} = 1 + \frac{R_4}{R_2 + R_1}$$

In addition, some applications, such as those for video, may require the use of 75-Ω cable and 75-Ω EVM input termination and output isolation resistors.

Any of the resistors on the EVM board can be replaced with a resistor of a different value; however, care must be taken because the surface-mount solder pads on the board are somewhat fragile and will not survive many desoldering/soldering operations.

Note that external factors can significantly affect the effective gain of the EVM. For example, connecting test equipment with 50-Ω input impedance to the EVM output will divide the output signal level by a factor of 2 (assuming the output isolation resistor on the EVM board remains 50 Ω). Similar effects can occur at the input, depending upon how the input signal sources are configured. The gain equations given above assume no signal loss in either the input or the output.

The EVM circuit board is an excellent example of proper board layout for high-speed amplifier designs and can be used as a guide for user application board layouts.

1.3 THS4061 EVM Specifications

Supply voltage range, $\pm V_{CC}$	$\pm 5\text{ V}$ to $\pm 15\text{ V}$
Supply current, I_{CC}	7.8 mA
Input voltage, V_I	$\pm V_{CC}$, max
Output drive, I_O	100 mA, max

For complete THS4061 amplifier IC specifications and parameter measurement information, and additional application information, see the THS4061 data sheet, TI Literature Number SLOS234.

1.4 Using The THS4061 EVM

The THS4061 EVM operates from power-supply voltages ranging from $\pm 5\text{ V}$ to $\pm 15\text{ V}$. As shipped, the inverting input gain of the module is set to -1 , the noninverting input gain is set to 2, and signal inputs on the module are terminated for 50- Ω nominal impedance cables. An oscilloscope is typically used to view and analyze the EVM output signal.

- 1) Ensure that all power supplies are set to **OFF** before making power supply connections to the THS4061 EVM
- 2) Select the operating voltage for the EVM and connect appropriate split power supplies to the pads on the module marked **$-V_{CC}$** and **$+V_{CC}$**
- 3) Connect the power supply ground to the module pad marked **GND**
- 4) Connect an oscilloscope to the module SMA output connector (**J4**) through a 50- Ω nominal impedance cable (an oscilloscope having a 50- Ω input termination is preferred for examining very high frequency signals)
- 5) Set the power supply to **ON**
- 6) Connect the signal input to either the noninverting input (**J3**) for a gain of 2, or to the inverting input (**J2**) for a gain of -1

Note that each input connector is terminated with a 50- Ω resistor to ground. With a 50- Ω source impedance, the voltage seen by the THS4061 amplifier IC on the module will be $\frac{1}{2}$ the source signal voltage applied to the EVM.

- 7) Verify the output signal on the oscilloscope

Note that the signal shown on an oscilloscope with a 50- Ω input impedance will be $\frac{1}{2}$ the actual THS4061 amplifier IC output voltage. This is due to the voltage division between the output resistor (R5) and the oscilloscope input impedance.

1.5 THS4061 EVM Performance

Figure 1–3 shows the typical frequency response of the THS4061 EVM using the noninverting input ($G = 2$). Typical -0.1 dB bandwidths are 20 MHz and a -3 -dB bandwidth of 75 MHz with a ± 15 V power supply. These bandwidths remain consistent when the power supply drops to ± 5 V.

Figure 1–3. THS4061 EVM Frequency Response with Gain = +2

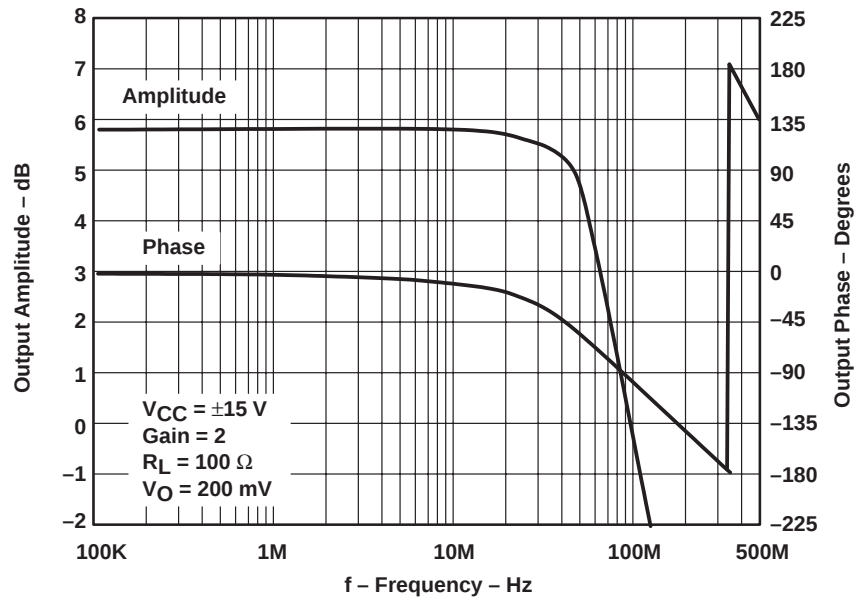
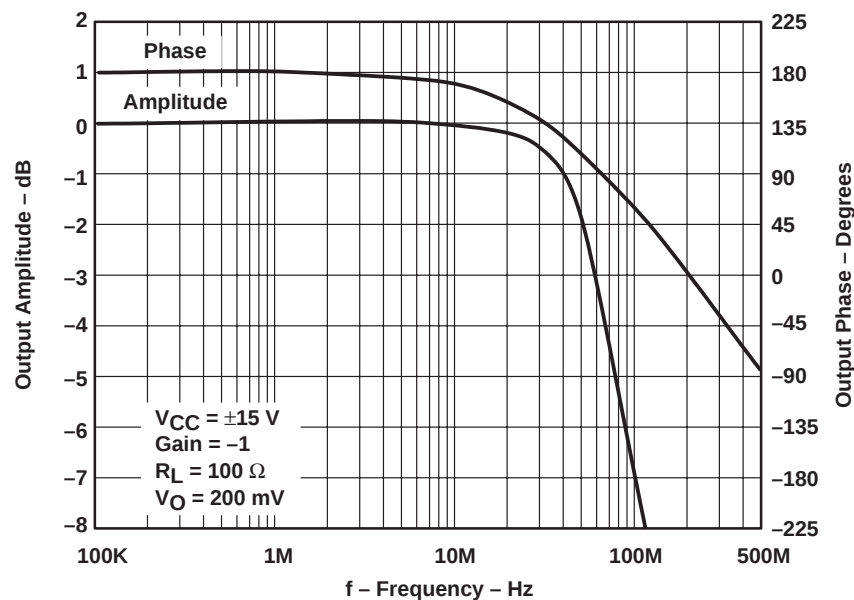


Figure 1–4 shows the typical frequency response of the THS4061 EVM using the inverting input ($G = -1$). Typical -0.1 dB bandwidths are 12 MHz and a -3 -dB bandwidth of 65 MHz with a ± 15 V power supply. These bandwidths remain consistent when the power supply drops to ± 5 V.

Figure 1–4. THS4061 EVM Frequency Response with Gain = -1



1.6 General High-Speed Amplifier Design Considerations

The THS4061 EVM layout has been designed and optimized for use with high-speed signals and can be used as an example when designing THS4061 applications. Careful attention has been given to component selection, grounding, power supply bypassing, and signal path layout. Disregard of these basic design considerations could result in less than optimum performance of the THS4061 high-speed, low-power operational amplifier.

Surface mount components were selected because of the extremely low lead inductance associated with this technology. Also, because surface mount components are physically small, the layout can be very compact. This helps minimize both stray inductance and capacitance.

Tantalum power supply bypass capacitors (C1 and C2) at the power input pads help supply currents for rapid, large signal changes at the amplifier output. The 0.1 μF power supply bypass capacitors (C3 and C4) were placed as close as possible to the IC power input pins in order to keep the PCB trace inductance to a minimum. This improves high-frequency bypassing and reduces harmonic distortion.

A proper ground plane on both sides of the PCB should always be used with high-speed circuit design. This provides low-inductive ground connections for return current paths. In the area of the amplifier IC input pins, however, the ground plane was removed to minimize stray capacitance and reduce ground plane noise coupling into these pins. This is especially important for the inverting pin while the amplifier is operating in the noninverting mode. Because the voltage at this pin swings directly with the noninverting input voltage, any stray capacitance would allow currents to flow into the ground plane, causing possible gain error and/or oscillation. Capacitance variations at the amplifier IC input pin of less than 1 pF can significantly affect the response of the amplifier.

In general, it is always best to keep signal lines as short and as straight as possible. Stripline techniques should also be incorporated when signal lines are greater than 1 inch in length. These traces should be designed with a characteristic impedance of either 50 Ω or 75 Ω , as required by the application. Such signal lines should also be properly terminated with an appropriate resistor.

Finally, proper termination of all inputs and outputs should be incorporated into the layout. Unterminated lines, such as coaxial cable, can appear to be a reactive load to the amplifier IC. By terminating a transmission line with its characteristic impedance, the amplifier's load then appears to be purely resistive and reflections are absorbed at each end of the line. Another advantage of using an output termination resistor is that capacitive loads are isolated from the amplifier output. This isolation helps minimize the reduction in amplifier phase-margin and improves the amplifier stability for improved performance such as reduced peaking and settling times.

Reference

This chapter includes a parts list and PCB layout illustrations for the THS4061 EVM.

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2.1 THS4061 High-Speed Operational Amplifier EVM Parts List

Table 2–1. THS4061 EVM Parts List

Reference	Description	Size	Manufacturer/Digi-Key Part Number
C1, C2	Capacitor, 6.8 μ F, 35 V, SM	D	Sprague 293D685X9035D2T
C3, C4	Capacitor, 0.1 μ F, ceramic, 10%, SM	1206	Sprague 11C1201E104M5NT
J1	Terminal Block		Digi-Key ED1515–ND
J2, J3, J4	Connector, SMA 50- Ω vertical PC mount, through-hole		Amphenol ARF1205–ND
R1, R3, R5	Resistor, 49.9 Ω , 1%, 1/8 W, SM	1206	Digi-Key P49.9CTR–ND
R2, R4	Resistor, 1 k Ω , 1%, 1/8 W, SM	1206	Digi-Key P1.0KCTR–ND
U1	IC, THS4061, operational amplifier	SOIC-8	TI THS4061
PCB1	PCB, THS4061 EVM		

2.2 THS4061 EVM Board Layouts

Board layout examples of the THS4061 EVM PCB are shown in the following illustrations. They are not to scale and appear here only as a reference.

Figure 2–1. THS4061 EVM Component Placement Silkscreen and Solder Pads

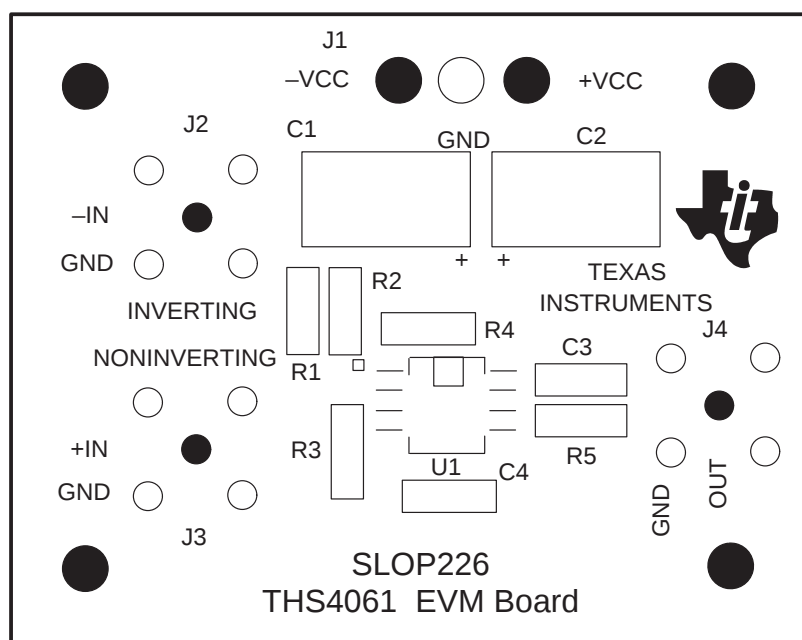


Figure 2–2. THS4061 EVM PC Board Layout – Component Side

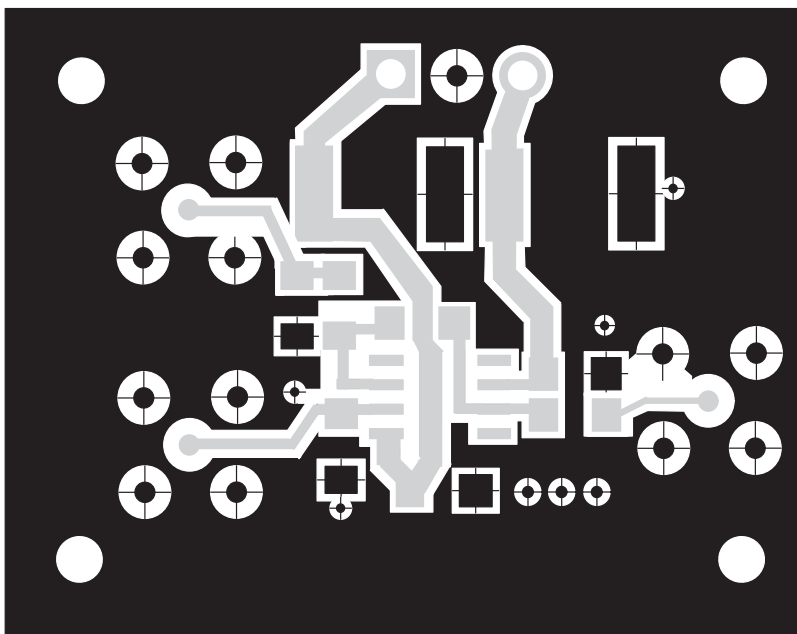


Figure 2–3. THS4061 EVM PC Board Layout – Back Side

